



Material Content Data Sheet



Sales Product Name		BCR 108W H6327		Issued		1. August 2018		
MA#		MA000852480						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		9	
	noble metal	gold	7440-57-5	0.005	0.08		841	
	inorganic material	silicon	7440-21-3	0.043	0.72	0.80	7181	8031
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1323	
	non noble metal	copper	7440-50-8	2.617	43.92	44.10	439105	440957
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	824	824
encapsulation	organic material	carbon black	1333-86-4	0.031	0.53		5262	
	plastics	epoxy resin	-	0.674	11.31		113142	
	inorganic material	silicondioxide	60676-86-0	2.431	40.78	52.62	407838	526242
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22266	22266
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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